## MN101E29 Series

Туре	MN101E29G	MN101EF29G
Internal ROM type	Mask ROM	FLASH
ROM (byte)	128K	128K+4K
RAM (byte)	6K	
Package (Lead-free)	LQFP100-P-1414, QFP100-P-1818B	
Minimum Instruction Execution Time	50 ns (at 2.2 V to 5.5 V, 20 MHz) *: at internal 2, 3, 4, 5, 6, 8, 10 times oscillation used	

#### ■ Interrupts

6 external interrupts. 28 internal interrupts

RESET. NMI. External 0 to 4. Timer 0 to 4. Timer 6. Timer 7 (2 systems). Timer 8 (2 systems). Timer 9 (2 systems). Time base. Serial 0 (2 systems). Serial 1 (2 systems). Serial 2 (2 systems). Serial 3 (2 systems). Serial 4. Serial 5. A/D conversion. Automatic transfer (2 systems). Key interrupt

#### ■ Timer Counter

8-bit timer  $\times$  7

Timer 0Timer J	oulse output. Event count. Added pulse (2-bit) type PWM output. Remote control carrier output. Simple
pulse w	ridth measurement. Real time output control
Timer 1Timer J	oulse output. Event count. 16-bit cascade connected (timer 0, 1). Timer synchronous output
Timer 2Timer J	bulse output. Event count. Added pulse (2-bit) type PWM output. Simple pulse width measurement. 24-bit
cascade	e connected (timer 0, 1, 2). Timer synchronous output. Real time output control
•	bulse output. Event count. Remote control carrier output. 16-bit cascade connected (timer 2, 3). 32-bit e connected (timer 0, 1, 2, 3)
Timer 4Timer J	pulse output. Added pulse (2-bit) type PWM output. Event count. Serial transfer clock output. Simple pulse
width r	neasurement
Timer 68-bit fr	eerun timer. Time base timer
Timer AEvent of	count. Baud rate timer. Clock output for peripheral function
16-bit timer $\times$ 3	
Timer 7Timer J	pulse output. Event count. High accuracy PWM. High performance IGBT output (cycle/duty continuous
	e). Timer synchronous output. Input capture (both edge available). Real time output control. Double buffer register
*	bulse output. Event count. High accuracy PWM output (cycle/duty continuous variable). Pulse width
•	ement. Input capture (both edge available). 32-bit cascade connected (timer 7, 8). 32-bit PWM output.
	onous output event. Double buffer compare register
•	, , ,
	pulse output. Event count. High accuracy PWM output (cycle/duty continuous variable). Pulse width
measur	ement. Input capture (both edge available). Real time output control. Double buffer compare register

#### Watchdog timer × 1

### ■ Serial interface

Synchronous type/UART (full-duplex)  $\times$  4: Serial 0 to 3 Synchronous type/Multi-master  $I^2C \times 1$ : Serial 4

 $I^2C$  slave  $\times$  1: Serial 5

#### ■ DMA controller

2 systems. Maximum transfer cycles are 255 Starting factor: External request. Internal event. Software

#### ■ I/O Pins

I/O 90: Common use. Specified pull-up/pull-down resistor available. Input/output selectable (bit unit)

#### ■ A/D converter

10-bit × 16 channels

#### ■ D/A converter

8-bit  $\times$  4 channels

#### ■ Display control function

LCD: 55 segments  $\times$  4 commons (Static, 1/2, 1/3, or 1/4 duty) 1/3 bias Usable if VLC1  $\leq$  VDD

Panasonic MAD00062FEM

#### ■ Special Ports

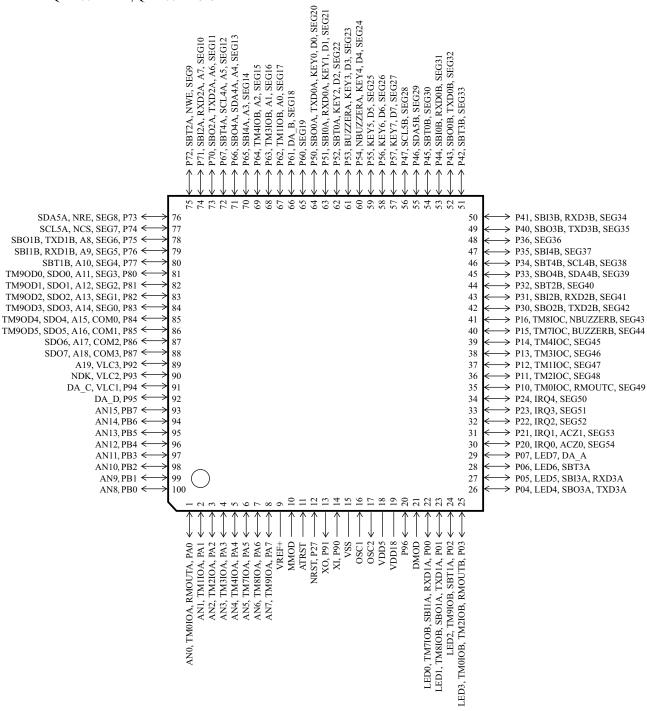
Buzzer output. Inverted buzzer output. Remote control carrier output. High-current drive port

#### ■ ROM Correction

Correcting address designation: Up to 7 addresses possible

#### ■ Pin Assignment

LQFP100-P-1414, QFP100-P-1818B



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